

**IN THE DRAWINGS**

Corrected drawings are supplied herewith, each labeled as "REPLACEMENT SHEET". Applicant has provided corrected FIGS. that attempt to address the Examiner's objections related to cross-hatching.

### **REMARKS**

This paper responds to the Office Action mailed on January 12, 2005. Claims 1-21 are canceled and claims 22-39 are added such that claims 22-39 are now pending in this application.

#### **Affirmation of Election**

Restriction to one of the following claims was required:

- I. Claims 1-13, drawn to a method of forming via in a substrate;
- II. Claims 14-18, drawn to a substrate; or
- III. Claims 19-21 drawn to a computer system.

Applicant has canceled claims 1-21 such that the restriction is moot.

#### **§102 Rejection of the Claims**

Claims 14 -18 were rejected under 35 USC § 102(e) as being anticipated by Carpenter et al. (U.S. 6,810,583). Applicant has canceled claims 14-18 such that the rejection is moot.

#### **Reservation of Right to File Continuation or Divisional Applications**

Applicant respectfully traverses the rejection listed above and reserves the right to reintroduce any claims their original form in one or more continuation or divisional applications at a later date.

#### **Reservation of Right to Swear Behind References**

Applicant reserves the right to swear behind any references which are cited in a rejection under 35 U.S.C. §§102(a), 102(e), 103/102(a), and 103/102(e). Statements distinguishing the claimed subject matter over the cited references are not to be interpreted as admissions that the references are prior art.

*New Claims 22-41*

Support for new claims 22-39 is found in the specification and the enclosed drawings. Applicant notes that the Carpenter et al. reference does not appear to include (among other items) “the first conductive layer including a first skip via extending through the first dielectric layer and a third dielectric layer”, or “the second conductive layer including a second via extending through the second dielectric layer” as recited in claim 22. Applicant further notes that the Carpenter et al. reference does not appear to include (among other items) “the first conductive layer including a first skip via extending through the first dielectric layer and a third dielectric layer”, or “the second conductive layer including a second skip via extending through the second dielectric layer and the fourth dielectric layer” as recited in claim 31.

Applicant respectfully directs the Examiner’s attention to the FIGS. in Carpenter et al. which illustrate that the metallizations (e.g., metallizations 31, 28 and 29) in Carpenter et al. are separate from the vias (e.g., vias 36, 24 , 26) such that the metallizations do not include vias. Applicant notes that none of metallizations disclosed in Carpenter et al. appear to include vias.

Allowance of claims 22-39 is respectfully requested.

AMENDMENT UNDER 37 C.F.R. 1.116 – EXPEDITED PROCEDURE

Serial Number: 10/742024

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Title: SELECTIVE PCB STIFFENING WITH PREFERENTIRALLY ORIENTED FIBERS

Assignee: Intel Corporation

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Conclusion

Applicant respectfully submits that the claims are in condition for allowance and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's attorney Andrew Peret at 262-646-7009, or the below-signed attorney at 612-349-9592, to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

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By his Representatives,

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Date April 12, 2005

By Ann M. McCrackin  
Ann M. McCrackin  
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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 12th day of April 2005.

Dennis J. Kemp

Name

[Signature]  
Signature